

In re Patent Application of:
BYUN, II ET AL.
Serial No. 10/522,049
Filing Date: JANUARY 20, 2005

In the Claims:

1. (Currently Amended) A method for connecting microcircuits comprising:

- (a) providing an insulating resin solution;
- (b) applying the insulating resin solution to each circuit board having circuit patterns;
- (c) aligning the circuit boards to face each other so that electrodes of the circuit boards face each other, in order to connect the corresponding electrodes of the circuit patterns formed in each circuit board;
- (d) positioning an anisotropic conductive adhesive between the circuit boards;
- (e) heating the circuit boards; and
- (f) applying a predetermined pressure to a side of each circuit board opposite the anisotropic conductive adhesive so that corresponding electrodes are connected to each other;

wherein in the (b) step, said insulating resin solution is formed on a plain portion and a side portion of the circuit patterns and a bottom portion of the circuit board.

2. (Previously Presented) The method of claim 1, wherein in the (a) step said insulating resin solution is prepared by dissolving a thermoplastic resin having a softening point in the range of 60 to 150°C or a compound of the thermoplastic resin into a solvent.

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3. (Original) The method of claim 2, wherein the thermoplastic resin is selected from the group of consisting of polyethylene resin, ethylene copolymer resin, ethylene vinyl acetate copolymer resin, ethylene-acrylic acid copolymer resin, ethylene acrylic acid ester copolymer resin, poly amide resin, poly ester resin, styrene butadiene copolymer resin, ethylene-propylene copolymer resin, acrylic acid ester rubber, acrylonitrile-butadiene copolymer resin, phenoxy resin, thermoplastic epoxy resin, poly urethane resin, poly vinyl acetal resin and poly vinyl butylal resin.

4. (Currently Amended) The method of claim 1 ~~claim 1~~, wherein in the (a) step said insulating resin solution is prepared by dissolving thermoplastic resin having a softening point in the range of 80 to 120°C or a compound of the thermoplastic resin into a soluble solvent.

5. (Previously Presented) The method of claim 1, wherein in the (b) step said insulating resin solution produces a film layer having a thickness of 0.1 to 5 μ m on the circuit board.

6. (Previously Presented) The method of claim 1, wherein in the (b) step said insulating resin solution produces a film layer having a thickness of 0.3 to 3 μ m on the circuit board.

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7. (Original) The method of claim 1, wherein the anisotropic conductive adhesive includes an insulating component, and conductive particles dispersed in the insulating component.

Claims 8-17 (Canceled).